

SolderKing

assembly materials ltd

Press Release

SolderKing Expands Solder Paste Range with SAC0307 Low-Silver Alloy Option

SolderKing Assembly Materials has launched SAC0307, a new low-silver addition to its SK P2-5 solder paste range. The new product enables manufacturers to review alloy selection while retaining the same flux chemistry and established process settings. This provides a practical option for high-mix production environments where material choices are assessed across different assemblies.



Chris Ward, Chief Operating Officer of SolderKing, said:

“Manufacturers are increasingly evaluating material strategies as product portfolios become more varied. With SAC0307, we’ve added an alloy option that sits within the existing SK P2-5 flux chemistry customers already use, enabling engineering teams to assess performance without altering core process conditions. That approach helps reduce risk during evaluation and supports stable, repeatable production.”

SK P2-5 SAC0307 is part of the company’s lead free, no clean solder paste portfolio and is suited to surface mount assembly where consistent stencil printing and reliable wetting are required across common PCB finishes including OSP, ENIG, silver, tin and HASL. The flux formulation is designed to minimise voiding and head-in-pillow defects, while complying with J-STD 004B and Belcore (ECM) requirements and leaving minimal residue after reflow.

The paste is available in both Type 4 (20–38µm) and Type 5 (15–25µm) powder grades, giving manufacturers options for fine pitch and higher density assemblies. Extended tack and open times in excess of three days allow greater flexibility during longer production runs or staged builds, while a 12-month refrigerated shelf life supports stock management.

Compatible with conventional air or nitrogen reflow, including convection and vapour phase systems, the SAC0307 can be used within established SMT production lines.

As with the wider SK P2-5 range, the paste incorporates high-purity solder powder exceeding EN 29453 and J-STD 006 requirements. Manufactured in the UK, it is supplied in packaging formats suited to both automated stencil printing and manual dispensing applications.

For further information, visit www.solderking.com or contact info@solderking.com.

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